

DC Input 16-Pin DMC[®] Half Pitch Mini-Flat

Phototransistor Optocoupler

Features

- High isolation 3750 V_{RMS}
- Patented coplanar structure DMC®
- Various CTR selection available
- DC input with transistor output
- Operating temperature range 55 °C to 125 °C
- RoHS and REACH compliance
- Halogen Free compliance
- Regulatory Approvals
 - ✓ UL UL1577 (pending approval)
 - ✓ VDE EN60747-5-5 (VDE0884-5)
 - ✓ CQC GB4943.1, GB8898

Description

The CTH281-4 series have four isolated channels, each channel contains a photo transistor optically coupled to two gallium arsenide Infrared-emitting diode in a 16-lead **DMC®** half pitch Mini-Flat package.

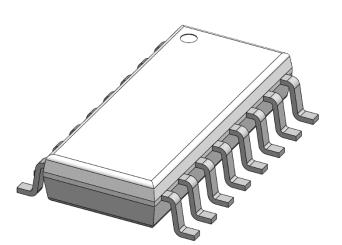
Applications

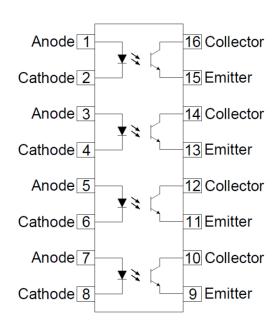
- DC-DC Converters
- Programmable controllers
- Telecommunication equipment

Schematic

 Hybrid substrates that require high density mounting

Package Outline







DC Input 16-Pin DMC[®] Half Pitch Mini-Flat

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Symbol	Parameters	Ratings	Units	Notes
Viso	Isolation voltage	3750	V _{RMS}	1
TOPR	Operating temperature	-55 ~ +125	°C	
T _{STG}	Storage temperature	-55 ~ +150	°C	
Tsol	Soldering temperature	260	°C	2
P _{TOT}	Total power dissipation	200	mW	
Emitter				
lF	Forward current	50	mA	3
F(TRANS)	Peak transient current (≤1µs P.W,300pps)	1	А	3
VR	Reverse voltage	6	V	3
PD	Power dissipation	70	mW	3
Detector	•			
Pc	Power dissipation	100	mW	3
BVCEO	Collector-Emitter Breakdown Voltage	80	V	3
B _{VECO}	Emitter-Collector Breakdown Voltage	7	V	3
lc	Collector Current	50	mA	3

Absolute Maximum Rating at 25°C

Notes

1. AC for 1 minute, $RH = 40 \sim 60\%$.

- 2. For reflow process
- 3. Each Channel



Electrical Characteristics T_A = 25°C, Each Channel (unless otherwise specified)

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I⊧=10mA	-	1.24	1.4	V	
CIN	Input Capacitance	f= 1MHz	-	10	30	pF	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
B _{VCEO}	Collector-Emitter Breakdown	Ic= 0.1mA	80	-	-	V	
BVECO	Emitter-Collector Breakdown	I _E = 0.1mA	7	-	-	V	
ICEO	Collector-Emitter Dark Current	V _{CE} = 20V, I _F =0mA	-	-	100	nA	

Transfer Characteristics

Symbol	Parame	eters	Test Conditions	Min	Тур	Max	Units	Notes
CTR	Current Transfer	CTH281-4	$I_{-} = F_{-} = F_{-} $	50	-	600	- %	
CIK	Ratio	CTH281-4GB	IF= 5mA, V _{CE} = 5V	100	-	600		
V _{CE(SAT)}	Collector-Emitter Saturation Voltage		I _F = 20mA, I _C = 1mA	-	0.1	0.2	V	
Rio	Isolation Resistance		V _{IO} = 500V _{DC}	5x10 ¹⁰			Ω	
CIO	Isolation Capacitance		f= 1MHz		0.5	1	pF	

Switching Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
tr	Rise Time		-	6	-		
t _f	Fall Time	I _C = 2mA, V _{CE} = 2V, R _L = 100Ω	-	8	-	μs	



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Phototransistor Optocoupler

Test Circuit

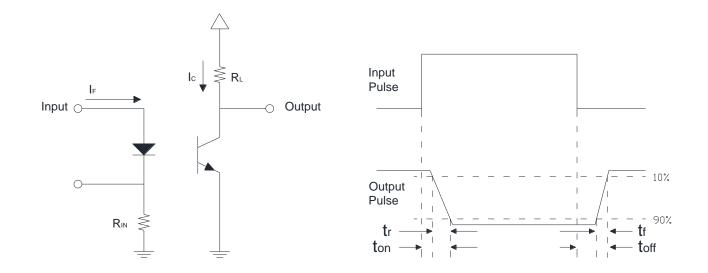


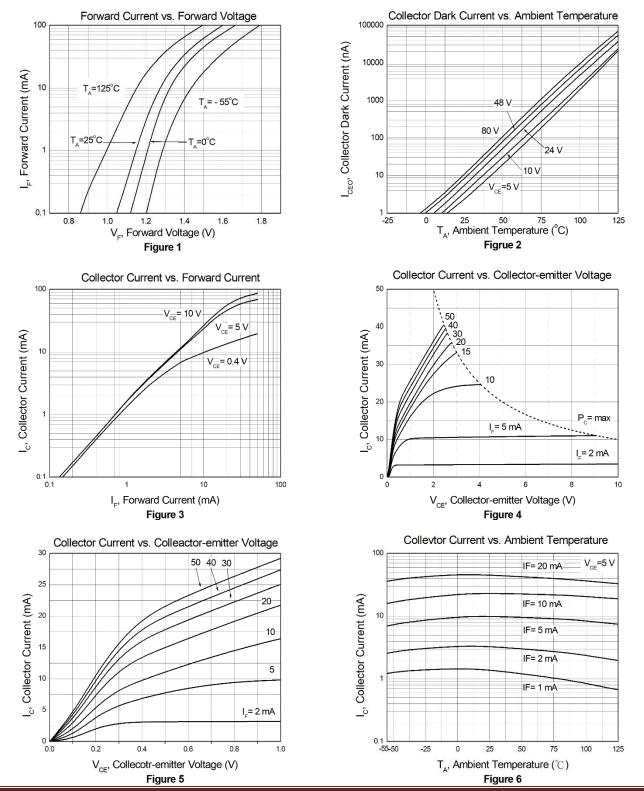
Figure 11: Switching Time Test Circuits



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Phototransistor Optocoupler

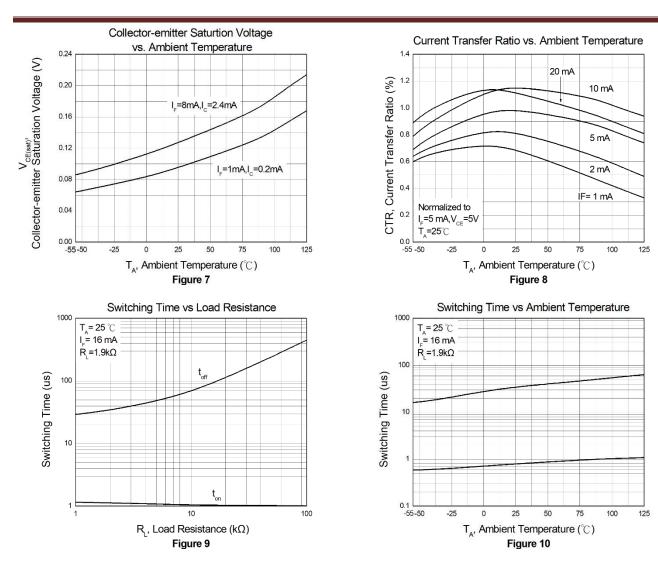
Typical Characteristic Curves





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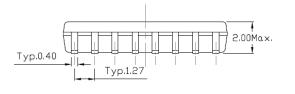
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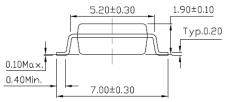


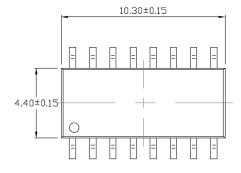


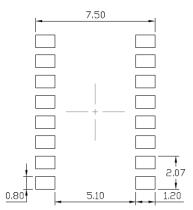
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Package Dimension Dimensions in mm unless otherwise stated

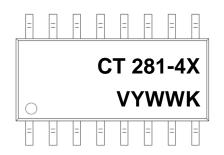








Marking Information



Note:

- CT : Denotes "CT Micro"
- 281-4 : Product Number
- X : CTR Rank
- V : VDE Safety Mark
- Y : Fiscal Year
- WW : Work Week
- K : Manufacturing Code



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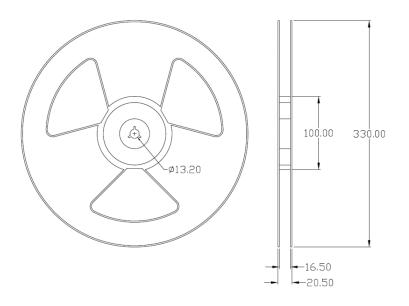
Ordering Information

CTH281-4X (V)(Z)

СТ	= Denotes "CT Micro"
H281-4	= Product Number
Х	= CTR Rank Option (Blank or GB)
V	= VDE Safety Mark Option (Blank or V)
Z	= Tape and reel Option (T1 or T2)

Option	Description	Quantity
T1	Surface Mount Lead Forming – With Option 1 Taping	2000 Units/Reel
T2	Surface Mount Lead Forming – With Option 1 Taping	2000 Units/Reel

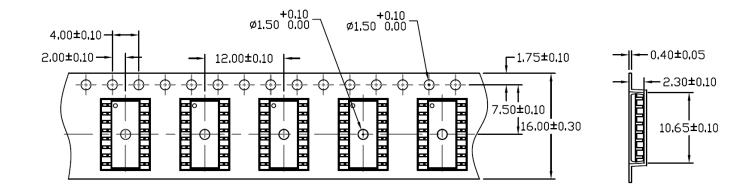
Reel Dimension All dimensions are in mm, unless otherwise stated



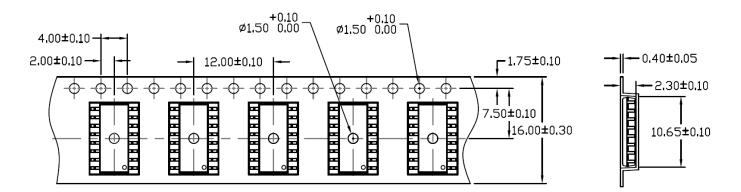


Carrier Tape Specifications Dimensions in mm unless otherwise stated

Option T1



Option T2





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Solderability spec (Follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

Wave soldering (Follow the JEDEC standard JESD22-A111)

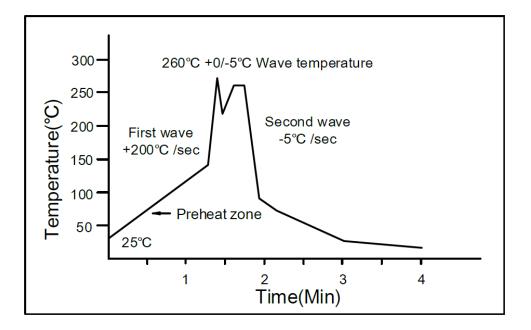
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature: 25 to 140°C.

Preheat time: 30 to 80 sec.



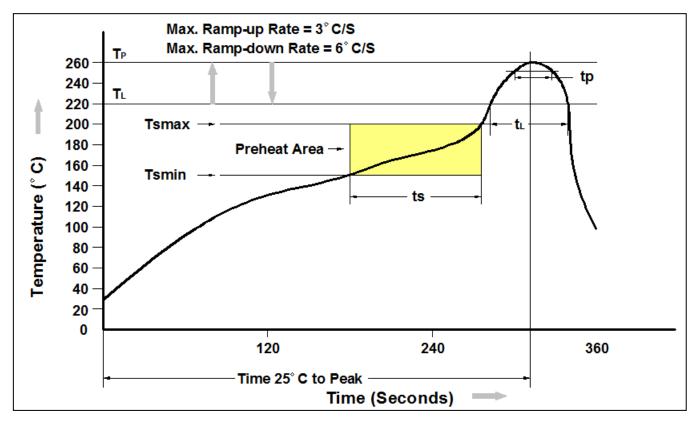
Hand soldering by soldering iron (Follow the standard MIL-STD 202G, Method 210F)

Allow single lead soldering in every single process. One time soldering is recommended. Temperature: 350±10°C Time: 5 sec max.



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Reflow Profile (follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t _P)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate $(T_P \text{ to } T_L)$	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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